

2023/10

ADEKA REMYLOP FL-340

■ Product Features

- One-component heat curing adhesive
- High thermal resistance
- High thermal conductivity

- Epoxy type (Halogen-free available)
- For screen printing

■ Properties (uncured)

Viscosity / 25°C	1 rpm	100	Pa · s
	10 rpm	65	Pa · s
Thixotropic value	1 rpm/10 rpm	1.5	
Specific gravity		2.2	
Filler content		80	wt %
Nonvolatile content		88	%
Pot Life	25 °C	168	hrs
Shelf Life	≤ 5 °C	4	months
Viscosity / 25°C	≤ -18 °C	12	months

■ 硬化物特性

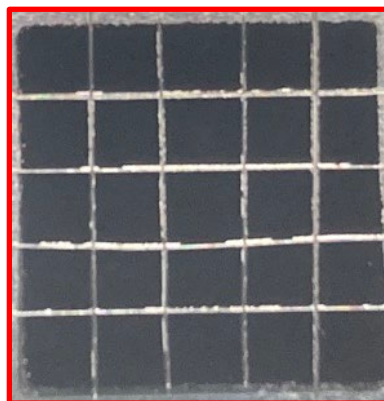
Glass transition temperature	TMA	—	°C
	DMA	216	°C
Hardness	ShoreD	> D80	
Storage modulus/ 25°C	DMA	13.2	GPa
Coefficient of linear expansion	α1	18	ppm
	α2	1.5~2.0	W/m · K

DMA : TA RSA-G2 25 – 300 °C (10 °C/min),
curing condition ; 120 °C/1 hr → 175 °C/1 hr
TMA : SII TMA/SS6100 35 – 300 °C (5 °C/min)

■ Recommended Curing Conditions

120 °C/1 hr → 175 °C/0.5 hr

■ Adhesion (JISK5600)



No peeling

■ Usage

- 【Storage】 Store in a sealed container at temperature below 5 °C (-18 °C recommended)
- 【Breaking the seal】 To prevent moisture condensation, please bring the product to room temperature before opening the package.
- 【Curing】 The adhesive must be heated sufficiently to reach the curing temperature. Curing conditions vary depending on the thermal capacity of the adherend and surrounding parts, the method of use, and the amount of coating applied.
- 【Disposal】 Please refer to SDS for proper treatment.
- 【Others】 Please contact us at the following

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